

Integral metal plane for power or ground

(0,80mm) .0315" **QSE SERIES**

HIGH SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QSE

Insulator Material: Liquid Crystal Polymer Terminal Material: Phosphor Bronze Plating:

Au or Šn over 50μ" (1,27μm) Ni Current Rating: Contacts: 1.3A @ 95°C Ground Plane: 10.1A @ 95°C Operating Temp Range:
-55°C to +125°C
Voltage Rating:
225 VAC (5mm Stack Height)

Max Cycles:

Unmating Force (-RT1 option):
-RT1 option increases unmating force up to 50% RoHS Compliant:

Processing: Lead-Free Solderable:

SMT Lead Coplanarity: (0,10mm) .004" max (020-060) (0,15mm) .006" max (080) **Board Stacking:**

For applications requiring more than two connectors per board or 4 banks or more, contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

- 14mm, 15mm, 22mm and 30mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount
- 100 positions per row
- Guide Posts and Friction Lock options.

Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.



QSE

DIA

-01

Cable Mates: EQCD, EQSD, EQDP, EQRF (See Application Specific note)



Call Samtec for maximum cycles mated with QTE

QTE/QSE 5mm Stack Height	Туре	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	7.5 GHz / 15 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps	
+D (

*Performance data includes effects of a non-optimized PCB. Test board losses de-embedded from performance data

Performance data for other stack heights and complete test data available at www.samtec.com?QSE or contact sig@samtec.com

PINS PER ROW

NO. OF PAIRS

m m m 1 Blade & Beam Design **ALSO**

AVAILABLE

Board Spacing Standoffs. See SO Series.

XAUI PCI Express® SATA MGT (Rocket I/O)

8

8 9

8

8

–D

= Single

Ended

= Differential

(-01 only)

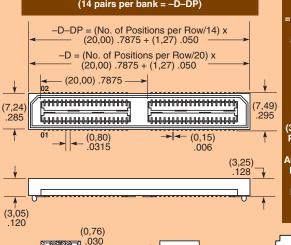
D-DP

InfiniBand™ Download app notes at www.samtec.com/appnote Contact SIG @ samtec.com for questions on protocols

OTHER OPTION



-014, -028, -042, -056(14 pairs per bank = -D-DP)



= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

PLATING

OPTION

01

= 10µ" (0,25µm) Gold on Signal Pins and Ground Plane Matte Tin on tails

 $-C^*$ = Electro-Polished Selective 50μ" (1,27μm) min Au over 150μ" (3,81μm) Ni on Signal Pins in contact area, 10μ" (0,25μm) min Au over 50μ" (1,27μm) Ni on Ground Plane in contact area. Matte Tin over 50µ" (1,27µm) min Ni on all solder tails

(0.64)

025

MATED QTE LEAD HEIGHT WITH QSE -01 (5,00) .197 -02 (8,00) .315 -03(11,00) .433 -04 (16,00) .630 (19,00) .748 -05-07 (25,00) .984

*Processing conditions will affect mated height.

(8,25mm) .325 **DIA Polyimide** Film Pick & Place Pad

–TR

= Tape & Reel Packaging (N/A on 56 & 80 positions)

-RT1

= Retention Option (N/A on 56 & 80 positions or -L (latch) option)

—L

= Latching Option (N/A on 42, 56, 60 & 80 positions or RT1 option)

Due to technical progress, all designs, specifications and components are subject to change without notice. WWW.SAMTEC.COM

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DIA